



Dual N-Channel MOSFET, 30V, 12mΩ, 10A

General Description

The VAD32140 utilizes the advanced Trench technology and low resistance package to achieve extremely low on-resistance device which makes the system design an efficient and reliable solution for use in a wide variety of applications.

Features

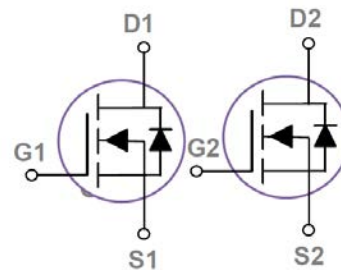
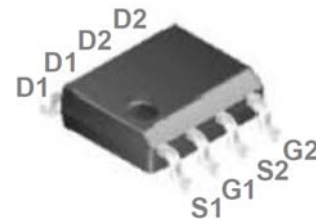
- 30V, 10A, $R_{DS(on)}=12m\Omega@V_{GS}=10V$
- High Efficiency
- Improved dv/dt, di/dt capability
- 100% EAS Guaranteed
- Green Device

Application

Lithium-ion Battery Pack Applications

Product Summary

| | | |
|---------------|--------------|-------|
| $V_{(BR)DSS}$ | $R_{(DS)on}$ | I_D |
| 30V | 12 mΩ | 10A |



Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit | Condition |
|---|------------|------------|------------|--------------------------------------|
| Drain-Source Voltage | V_{DS} | 30 | V | |
| Continuous drain current ⁽¹⁾ | I_D | 10 8 | A | $T_A=25^\circ C$ $T_A=70^\circ C$ |
| Gate-Source Voltage | V_{GS} | ± 20 | V | Static |
| Pulsed drain current ⁽²⁾ | I_{DM} | 36 | A | $T_C=25^\circ C$ |
| Power dissipation @ $T_C=25^\circ C$ | P_{diss} | 1.5 | W | $T_A=25^\circ C$ |
| Continuous diode forward current | I_S | 9 | A | $T_C=25^\circ C$ |
| Storage Temperature Range | T_{STG} | -55 to 150 | $^\circ C$ | |
| Operation Junction Temperature Range | T_J | -55 to 150 | $^\circ C$ | |

(1) Limited by $T_{j,max}$.

(2) Pulse width T_P limited by $T_{j,max}$



Thermal characteristics

| Symbol | Parameter | Min | Typ | Max | Unit |
|------------|---|-----|-----|-----|------|
| R_{thJA} | Thermal resistance, junction-ambient, max | --- | --- | 85 | °C/W |
| T_{sold} | Soldering temperature, max | --- | --- | 260 | °C |

Package and Ordering Information

| Device | Package |
|----------|---------|
| VAD3214O | SOP8 |



Electrical Characteristics ($T_j=25^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Min | Typ | Max | Unit | Test Condition |
|-------------------------------------|---------------|-----|------|------|---------------|--|
| Static Characteristic | | | | | | |
| Drain-Source breakdown Voltage | $V_{(BR)DSS}$ | 30 | --- | --- | V | $V_{GS}=0V, I_D=0.25mA$ |
| Gate Threshold Voltage | $V_{(GS)th}$ | 1.2 | --- | 2.5 | V | $V_{DS}=V_{GS}, I_D=0.25mA$ |
| Drain-Source on resistance | $R_{(DS)on}$ | --- | --- | 12 | m Ω | $V_{GS}=10V, I_D=8A, T_j=25^\circ\text{C}$ |
| | | --- | --- | 18 | m Ω | $V_{GS}=4.5V, I_D=6A, T_j=25^\circ\text{C}$ |
| Zero gate voltage drain current | I_{DSS} | --- | --- | 1 | μA | $V_{DS}=24V, V_{GS}=0V, T_j=25^\circ\text{C}$ |
| Gate-Source leakage current | I_{GSS} | --- | --- | 100 | nA | $V_{GS}=\pm 20V, V_{DS}=0V$ |
| Dynamic Characteristic | | | | | | |
| Input Capacitance | C_{iss} | 760 | 940 | 1175 | pF | $V_{GS}=0V, V_{DS}=15V, f=1MHz$ |
| Output Capacitance | C_{oss} | 92 | 131 | 163 | pF | $V_{GS}=0V, V_{DS}=15V, f=1MHz$ |
| Reverse Transfer Capacitance | C_{rss} | 76 | 109 | 153 | pF | $V_{GS}=0V, V_{DS}=15V, f=1MHz$ |
| Turn-on delay time | $T_{d(on)}$ | --- | 4.2 | --- | nS | $V_{DD}=15V, V_{GS}=10V, I_D=8A, R_G=1.5\Omega;$ |
| Rise time | T_r | --- | 8.2 | --- | nS | |
| Turn-off delay time | $T_{d(off)}$ | --- | 31 | --- | nS | |
| Fall time | T_f | --- | 4 | --- | nS | |
| Gate Charge Characteristic | | | | | | |
| Gate to source charge | Q_{gs} | --- | 3.88 | --- | nC | $V_{DD}=15V, I_D=8A, V_{GS}=4.5V$ |
| Gate to drain charge | Q_{gd} | --- | 3.44 | --- | nC | |
| Gate charge total | Q_g | --- | 9.63 | --- | nC | |
| Reverse diode characteristic | | | | | | |
| Diode forward voltage | V_{FD} | --- | --- | 1 | V | $V_{GS}=0V, I_F=1A, T_j=25^\circ\text{C}$ |
| Continuous Source Current | I_{esc} | --- | --- | 9 | A | $V_G=V_D=0V, \text{Force current}$ |
| Reverse Recovery Time | t_{rr} | --- | 8 | --- | nS | $I_F=8A, di/dt=100A/\mu\text{S}, T_j=25^\circ\text{C}$ |
| Reverse Recovery Charge | Q_{rr} | --- | 2.9 | --- | nC | |

Electrical Characteristic Diagrams

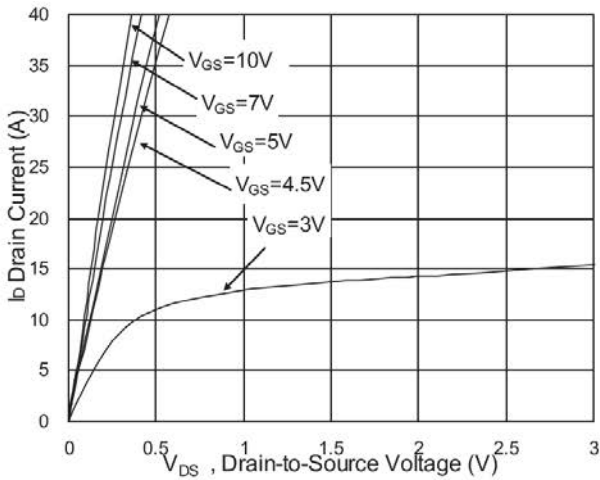


Figure 1 Typical Output Characteristic

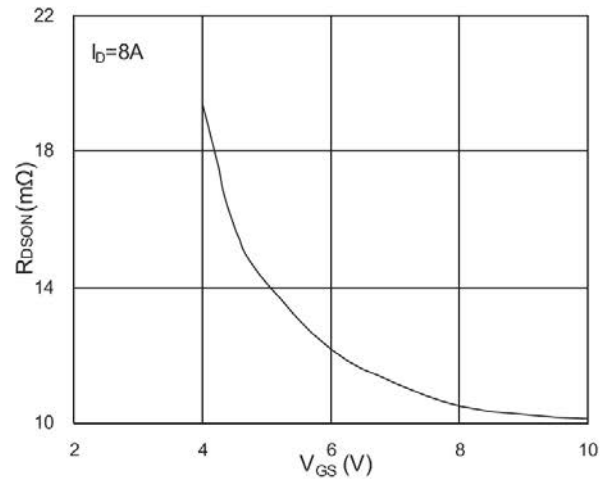


Figure 2 On-Resistance vs. GS voltage

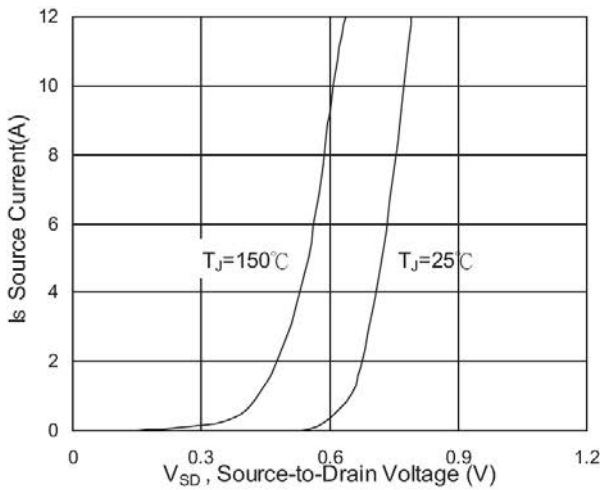


Figure 3 Forward Characteristic of Reverse

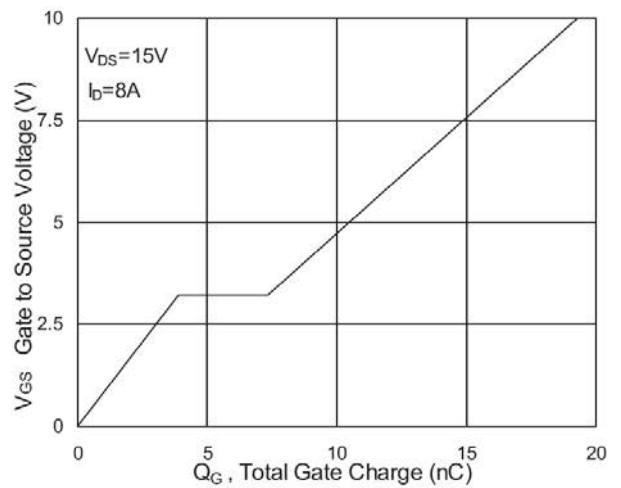


Figure 4 Gate Charge Waveform

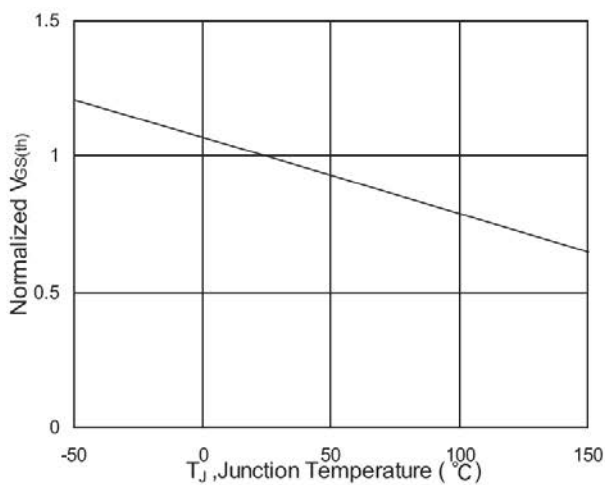


Figure 5 Normalized $V_{GS(th)}$ vs. T_J

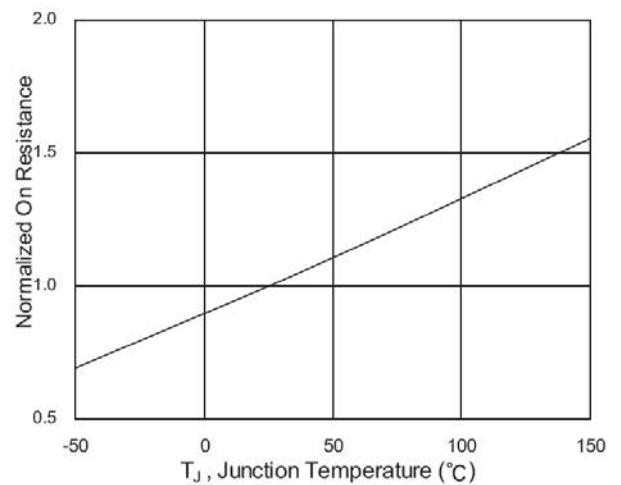


Figure 6 Normalized $R_{DS(on)}$ vs. T_J

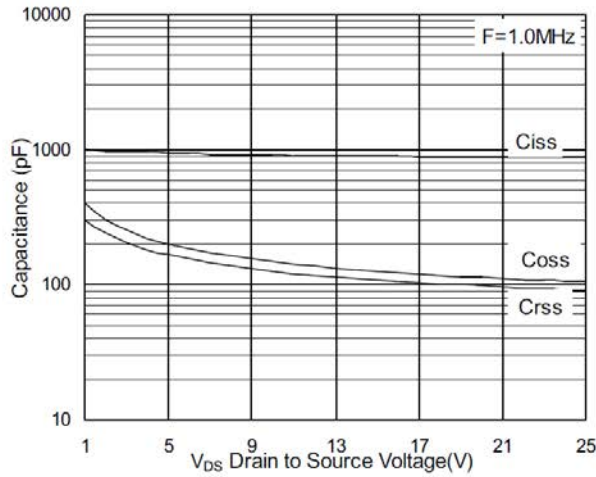


Figure 7 Capacitance Characteristic

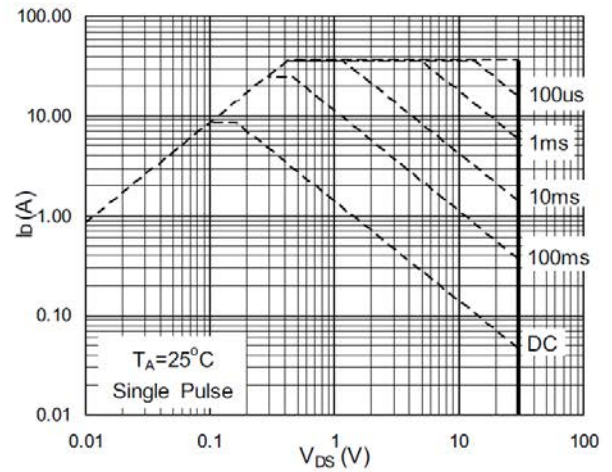


Figure 8 Safe Operating Area

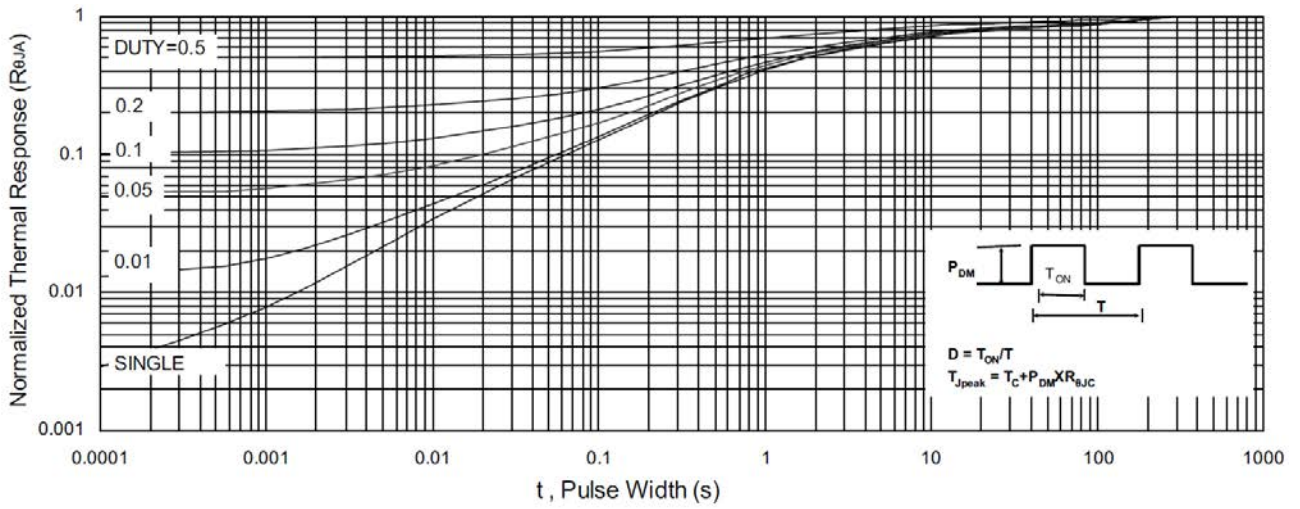


Figure 9 Normalized Maximum Transient Thermal Impedance

Parameter Test Circuits

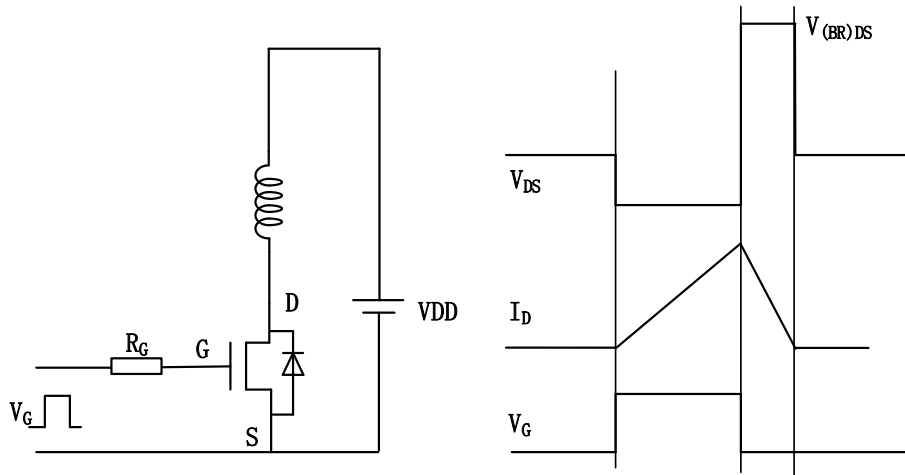


Figure 10 Unclamped Inductive Switching (UIS) Test circuit and waveforms

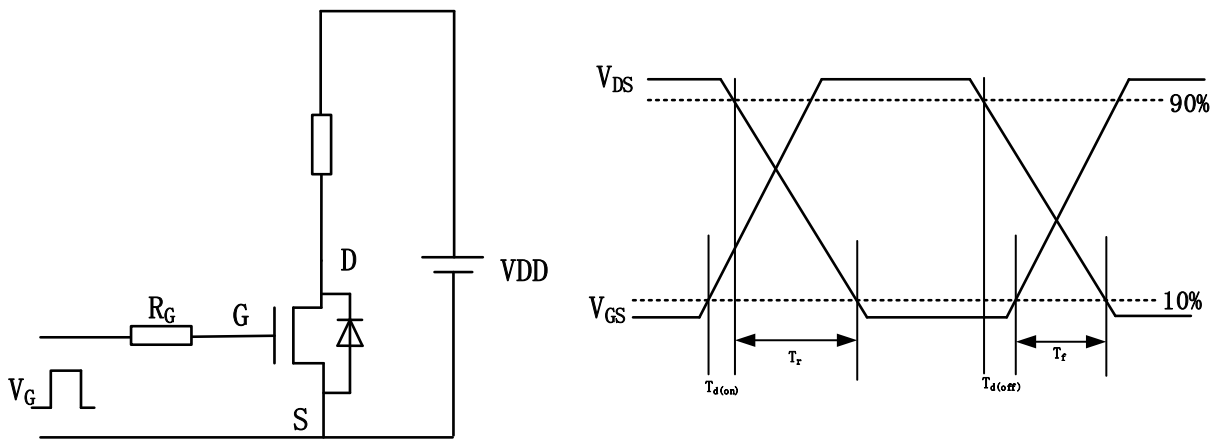


Figure 11 Resistive Switching time Test circuit and waveforms

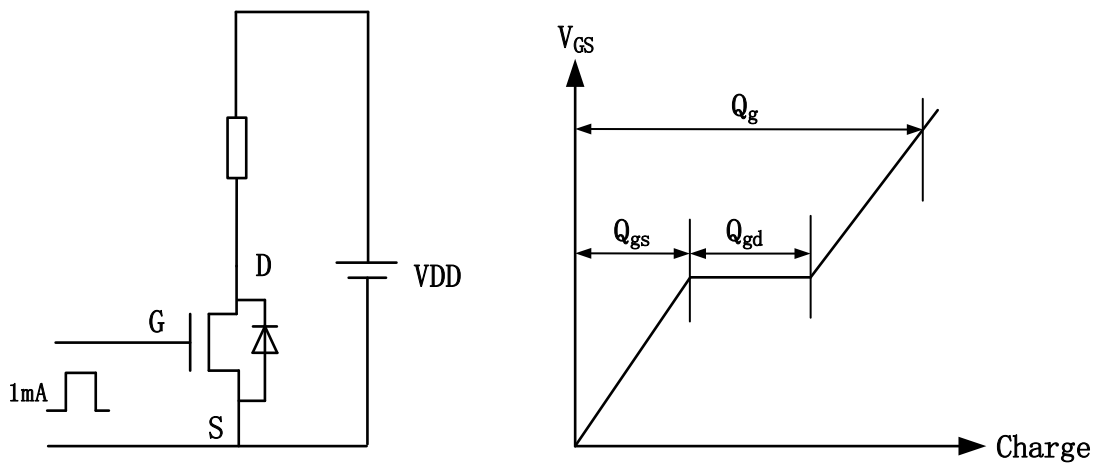
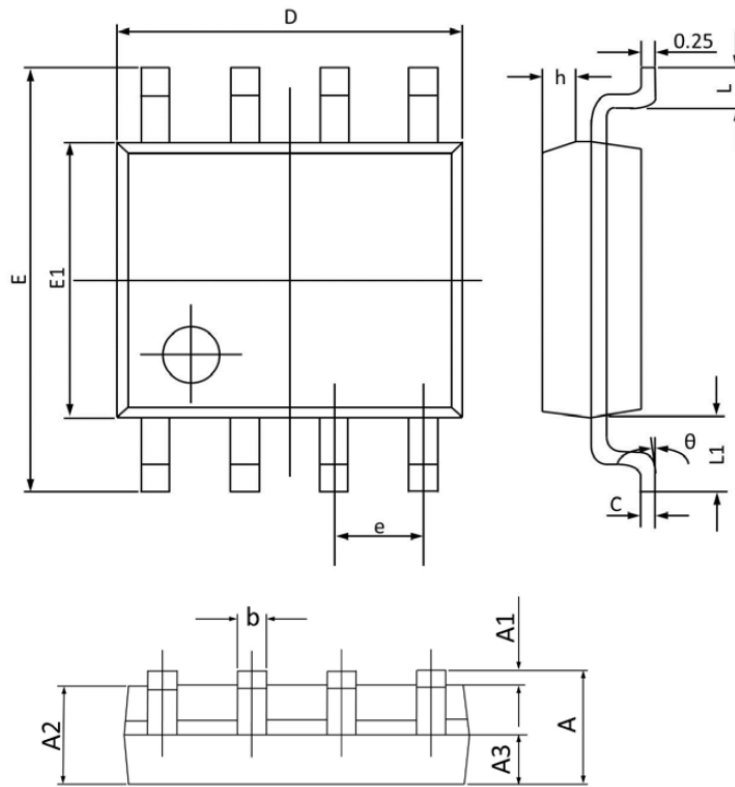


Figure 12 Gate charge Test circuit and waveforms



Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.350 | 1.750 | 0.053 | 0.068 |
| A1 | 0.100 | 0.250 | 0.004 | 0.009 |
| A2 | 1.300 | 1.500 | 0.052 | 0.059 |
| A3 | 0.600 | 0.700 | 0.024 | 0.027 |
| b | 0.390 | 0.480 | 0.016 | 0.018 |
| c | 0.210 | 0.260 | 0.009 | 0.010 |
| D | 4.700 | 5.100 | 0.186 | 0.200 |
| E | 5.800 | 6.200 | 0.229 | 0.244 |
| E1 | 3.700 | 4.100 | 0.146 | 0.161 |
| e | 1.270(BSC) | | 0.050(BSC) | |
| h | 0.250 | 0.500 | 0.010 | 0.019 |
| L | 0.500 | 0.800 | 0.019 | 0.031 |
| L1 | 1.050(BSC) | | 0.041(BSC) | |
| θ | 0° | 8° | 0° | 8° |

单击下面可查看定价，库存，交付和生命周期等信息

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